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Contents

vii Conference Committee

	NOVEL OPTICAL INTERCONNECT AND NEURAL NETWORK SYSTEMS
13372 02	Overcoming challenges of co-integrated optics to advance accelerated computing (Invited Paper) [13372-2]
	PIC INTEGRATION AND COUPLING
13372 03	Coupling manipulation enabled high-performance devices (Invited Paper) [13372-6]
13372 04	Innovations in fibre array coupling and integration for high-bandwidth FPGA multichip packages (Invited Paper) [13372-7]
13372 05	PANDA polarization-maintaining fiber for tight-bend applications and reflow-soldering [13372-9]
	PHOTONIC PACKAGING AND SYSTEM INTEGRATION
13372 06	Fully integrated single-chip silicon photonic processor for analog optical and microwave signals (Invited Paper) [13372-10]
13372 07	Versatile micro-optical coupling platform created by selective laser etching and smoothing of thin glass [13372-13]
13372 08	Semiconductorisation of photonic chip packaging [13372-55]
	WAFER SCALE TESTING AND GLASS WAVEGUIDES FOR BOARD LEVEL INTERCONNECTS
	WALER SCALE IESTING AND GEASS WAVEGUIDES FOR BOARD LEVEL INTERCONNECTS
13372 09	Glass substrate with integrated adiabatic waveguide bends for high-density fiber-to-chip coupling [13372-16]

HETEROGENEOUS INTEGRATION AND 3D PACKAGING

13372 0A	Active alignment of densely spaced optical fibers for high-accuracy fiber arrays manufacturing (Invited Paper) [13372-19]
13372 OB	Heterogeneous integration of GaAsSb and silicon via direct wafer bonding for high-speed avalanche photodiodes [13372-22]
13372 0C	Heterogeneous integration of InGaAs/GaAsSb superlattices with Si for e-SWIR sensors [13372-23]
13372 0D	Processing considerations for polishing PICs and waveguides [13372-36]
	PACKAGING TECHNOLOGY ADVANCEMENT
13372 OE	Recent advances in fiber-to-PIC packaging technologies for scalable manufacturing (Invited Paper) [13372-24]
13372 OF	Recent advances in optical interfacing microstructures fabricated through two-photon polymerization-based laser direct writing [13372-25]
13372 0G	Automated direct surface coupling of optical fibers to integrated photonics by laser welding [13372-26]
13372 OH	Optical performance of photonic wire bonds under temperature and humidity cycling [13372-27]
	NOVEL DEVICES AND MATERIALS FOR OPTICAL INTERCONNECTS
13372 01	Ferroelectrics for emergent silicon-integrated optical computing (Invited Paper) [13372-29]
13372 OJ	Silicon-organic hybrid (SOH) modulators for advanced photonic integration (Invited Paper) [13372-30]
13372 OK	Silicon plasmonic platform for interconnect applications (Invited Paper) [13372-34]
13372 OL	High power wavelength tunable external cavity laser for optical transmission (Invited Paper) [13372-33]
13372 OM	Key properties of adhesives for successful photonic packaging [13372-37]

O-E AND E-O CONVERSION AND 3D COUPLING

13372 ON	InP-based photodetector technologies for datacom applications (Invited Paper) [13372-38]
13372 00	A 20Gbps all-silicon APD-based receiver with CMOS IC [13372-39]
13372 OP	Machine-learning-driven optimization of vertical fiber-to-chip coupling system for copackaged optics and in-package optical I/O applications [13372-40]
13372 0Q	3D nanoprinting of beam shaping micro-optics on VCSEL chips integrated on a laser-written glass interposer $[13372\text{-}41]$
13372 OR	On-chip holographic gaussian-to-flat-top beam conversion for high-power photodiode [13372-42]
	MODULATOR, SWITCHING DEVICES, AND LOW LOSS INTERCONNECTS
13372 OT	Multicore fiber connectivity for submarine and data center applications (Invited Paper) [13372-44]
13372 OU	Power handling and polarization maintaining of photonic wire bonds [13372-46]
13372 0V	Back-compatibility of hollow core fibers with SMF infrastructure (Invited Paper) [13372-47]
	BUILDING BLOCKS FOR HETEROGENEOUS INTEGRATION
13372 OW	PCB-integrated flexo-printed optical networks structures [13372-49]
13372 0X	High-efficiency PAM4 ring modulator using W-Shaped PN junction [13372-51]
	POSTED SESSION
	POSTER SESSION
13372 0Y	Bend-optimized optical fiber with low multipath interference in the O-band [13372-54]
	DIGITAL POSTER SESSION
13372 OZ	Inverse-co-designed passive and active cascaded layers for compact and scalable optical switching [13372-12]
13372 10	Extending the reach of IM/DD links: chromatic dispersion compensation through MZI-based photonic processors [13372-50]